

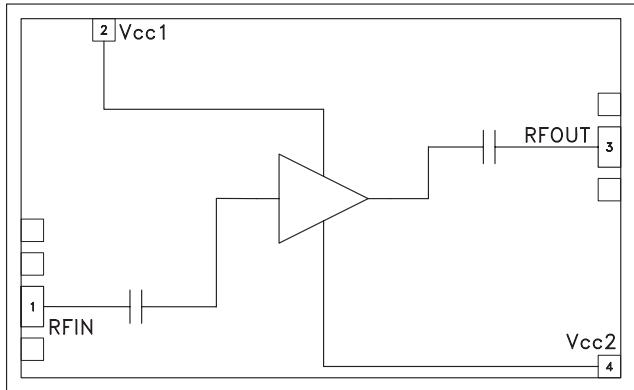
**GaAs InGaP HBT MMIC ULTRA LOW  
PHASE NOISE, DISTRIBUTED AMPLIFIER, 2 - 18 GHz**
**Typical Applications**

The HMC606 is ideal for:

- Radar, EW & ECM
- Microwave Radio
- Test Instrumentation
- Military & Space
- Fiber Optic Systems

**Features**

Ultra Low Phase Noise: -160 dBc/Hz @ 10 kHz  
 P1dB Output Power: +15 dBm  
 Gain: 14 dB  
 Output IP3: +27 dBm  
 Supply Voltage: +5V @ 64 mA  
 50 Ohm Matched Input/Output  
 Die Size: 2.80 x 1.73 x 0.1 mm

**Functional Diagram**

**General Description**

The HMC606 is a GaAs InGaP HBT MMIC Distributed Amplifier die which operates between 2 and 18 GHz. With an input signal of 12 GHz, the amplifier provides ultra low phase noise performance of -160 dBc/Hz at 10 kHz offset, representing a significant improvement over FET-based distributed amplifiers. The HMC606 provides 14 dB of small signal gain, +27 dBm output IP3 and +15 dBm of output power at 1 dB gain compression while requiring 64 mA from a +5V supply. The HMC606 amplifier I/Os are internally matched to 50 Ohms facilitating easy integration into Multi-Chip-Modules (MCMs). All data is taken with the chip in a 50 Ohm test fixture connected via 0.025 mm (1mil) diameter wire bonds of minimal length 0.31 mm (12 mils).

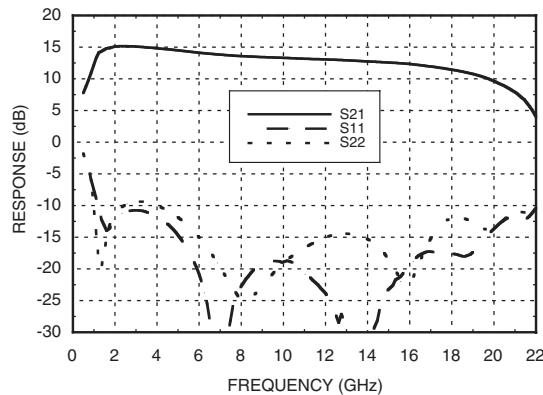
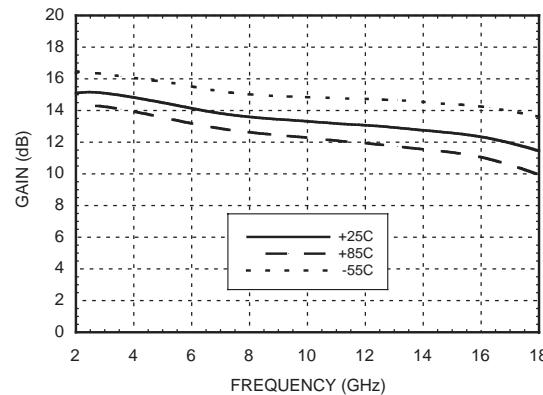
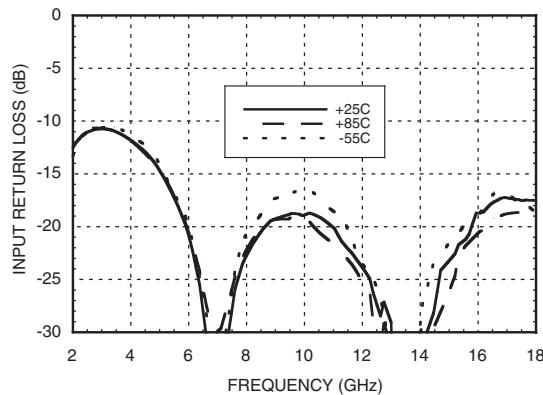
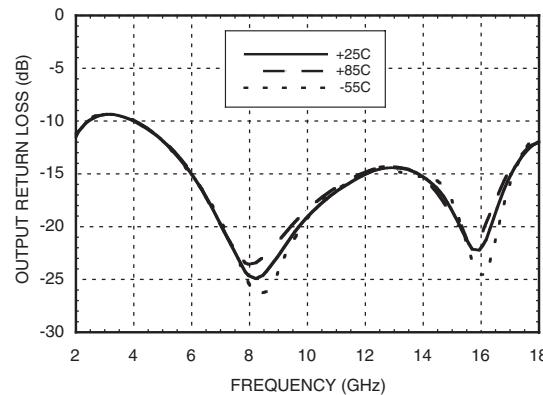
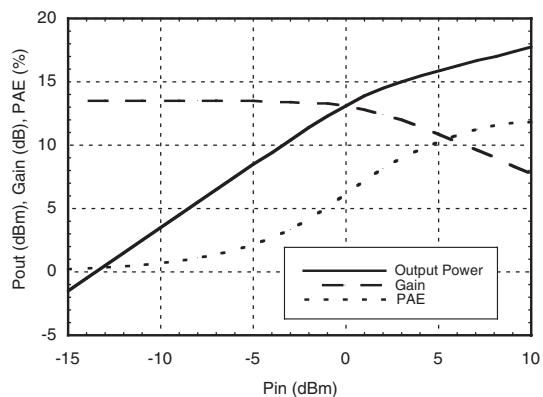
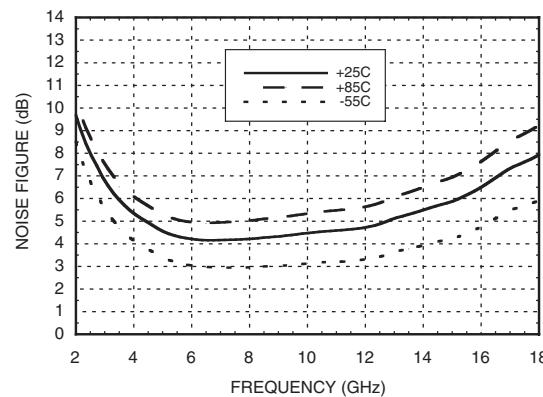
**Electrical Specifications,  $T_A = +25^\circ C$ ,  $Vcc1 = Vcc2 = 5V$** 

| Parameter                                | Min. | Typ.      | Max. | Min. | Typ.      | Max. | Units  |
|--|------|-----------|------|------|-----------|------|--------|
| Frequency Range                          |      | 2 - 12    |      |      | 12 - 18   |      | GHz    |
| Gain                                     | 11   | 14.0      |      | 10   | 13        |      | dB     |
| Gain Flatness                            |      | $\pm 1.0$ |      |      | $\pm 1.0$ |      | dB     |
| Gain Variation Over Temperature          |      | 0.021     |      |      | 0.25      |      | dB/ °C |
| Noise Figure                             |      | 4.5       |      |      | 6.5       |      | dB     |
| Input Return Loss                        |      | 20        |      |      | 22        |      | dB     |
| Output Return Loss                       |      | 15        |      |      | 15        |      | dB     |
| Output Power for 1 dB Compression (P1dB) | 12   | 15        |      | 10   | 13        |      | dBm    |
| Saturated Output Power (Psat)            |      | 18        |      |      | 15        |      | dBm    |
| Output Third Order Intercept (IP3)       |      | 27        |      |      | 22        |      | dBm    |
| Phase Noise @ 100 Hz                     |      | -140      |      |      | -140      |      | dBc/Hz |
| Phase Noise @ 1 kHz                      |      | -150      |      |      | -150      |      | dBc/Hz |
| Phase Noise @ 10 kHz                     |      | -160      |      |      | -160      |      | dBc/Hz |
| Phase Noise @ 1 MHz                      |      | -170      |      |      | -170      |      | dBc/Hz |
| Supply Current                           |      | 64        | 80   |      | 64        | 80   | mA     |

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:

20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373

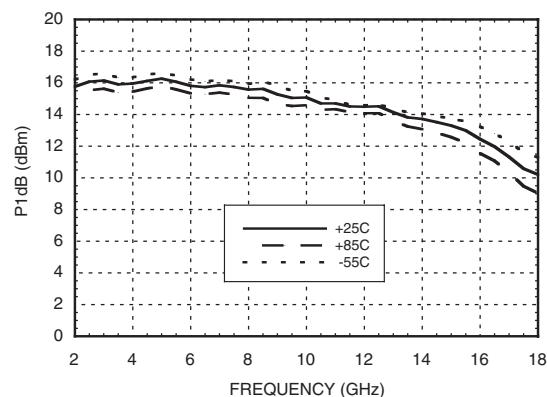
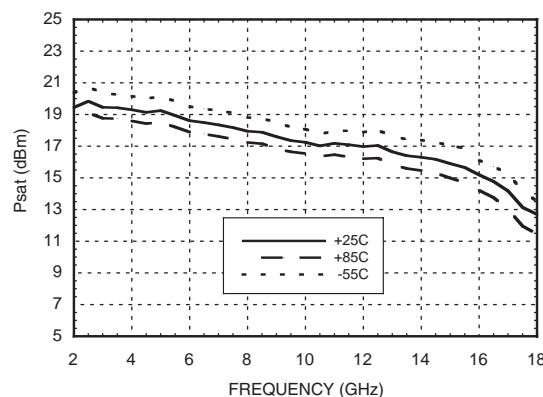
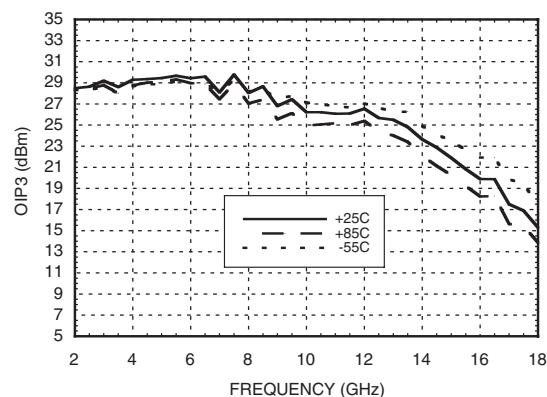
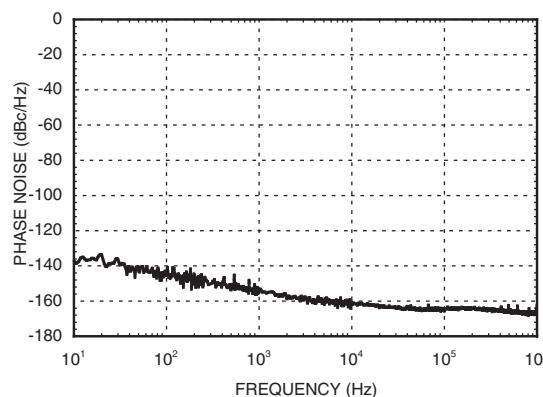
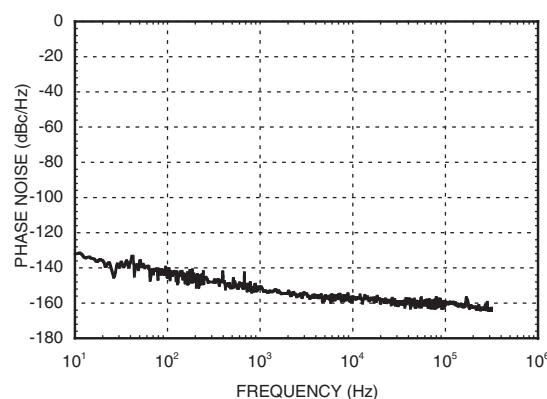
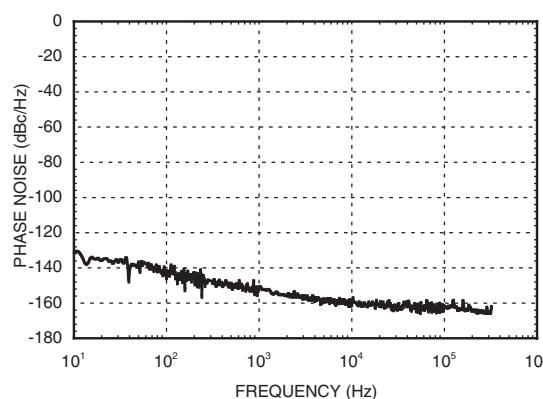
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**Gain & Return Loss****Gain vs. Temperature****Input Return Loss vs. Temperature****Output Return Loss vs. Temperature****Power Compression****Noise Figure vs. Temperature**

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1

AMPLIFIERS - CHIP

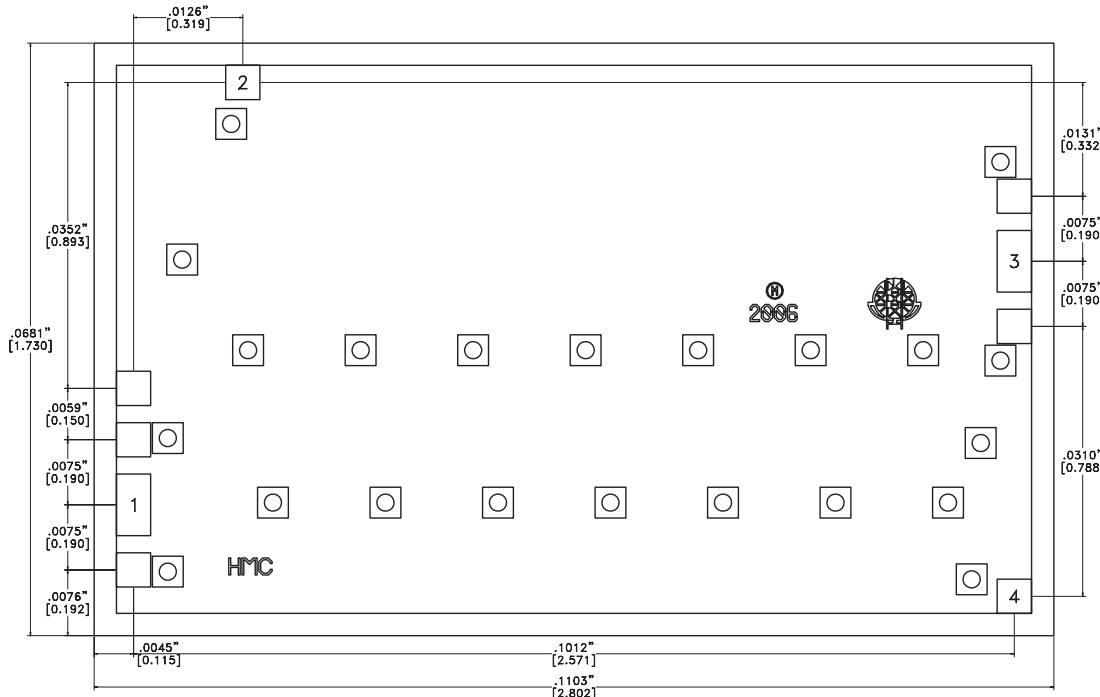
**P1dB vs. Temperature****Psat vs. Temperature****Output IP3 vs. Temperature****Phase Noise @ 12 GHz****Phase Noise at P1dB @ 12 GHz****Phase Noise at Psat @ 12 GHz**

**GaAs InGaP HBT MMIC ULTRA LOW  
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**Absolute Maximum Ratings**

|   |                |
|---|----------------|
| Vdd1= Vdd2= 5V  | 7V             |
| RF Input Power (RFin)   | +15 dBm        |
| Channel Temperature   | 175 °C         |
| Continuous Pdiss (T = 85 °C)<br>(derate 14.6 mW/°C above 85 °C) | 1.32 W         |
| Thermal Resistance<br>(channel to die bottom)                   | 68.37 °C/W     |
| Storage Temperature   | -65 to +150 °C |
| Operating Temperature   | -55 to +85 °C  |

**Typical Supply Current vs. Vcc1, Vcc2**

| Vcc1= Vcc2 (V) | Icc1 + Icc2 (mA) |
|----------------|------------------|
| +4.5           | 53               |
| +5.0           | 64               |
| +5.5           | 74               |


**ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS**
**Outline Drawing**

**Die Packaging Information <sup>[1]</sup>**

| Standard | Alternate |
|----------|-----------|
| GP-1     | [2]       |

[1] Refer to the "Packaging Information" section for die packaging dimensions.

[2] For alternate packaging information contact Hittite Microwave Corporation.

**NOTES:**

1. ALL DIMENSIONS IN INCHES [MILLIMETERS]
2. NO CONNECTION REQUIRED FOR UNLABELED BOND PADS
3. DIE THICKNESS IS 0.004 (0.100)
4. TYPICAL BOND PAD IS 0.004 (0.100) SQUARE
5. BACKSIDE METALLIZATION: GOLD
6. BACKSIDE METAL IS GROUND
7. BOND PAD METALLIZATION: GOLD

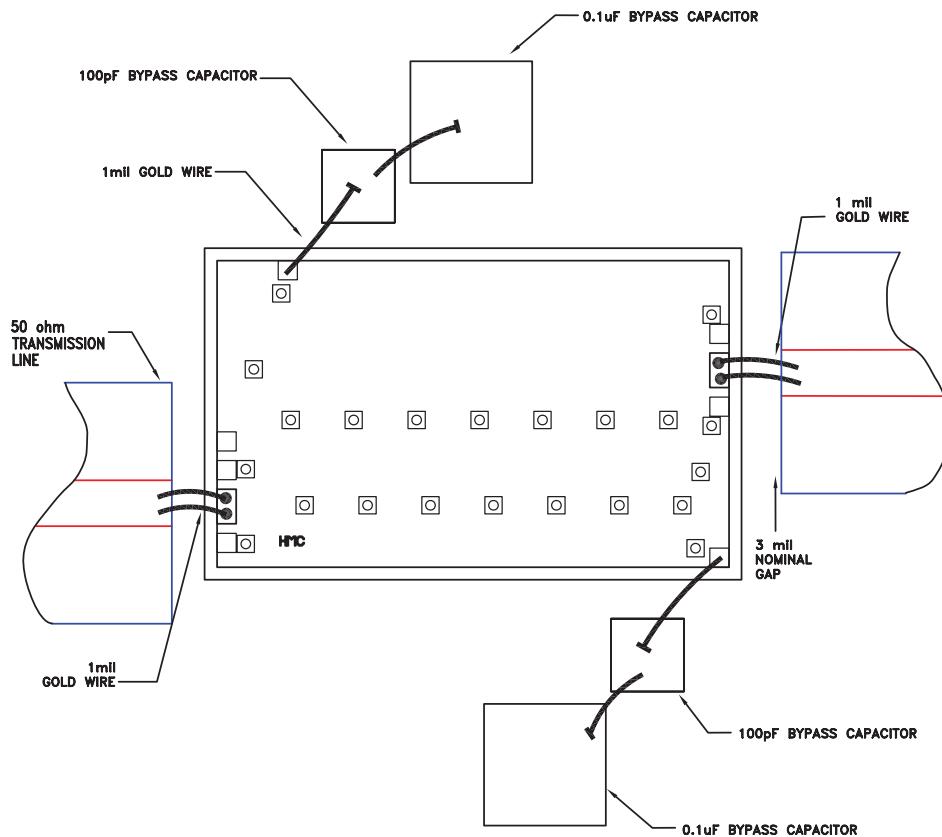
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**Pad Descriptions**

| Pad Number | Function   | Description   | Interface Schematic  |
|------------|------------|---|--|
| 1          | RFIN       | This pin is AC coupled and matched to 50 Ohms from 2 - 18 GHz | RFIN $\text{---} \parallel \text{---}$   |
| 2, 4       | Vcc1, Vcc2 | Vcc1= Vcc2= 5V  | $\text{---} \parallel \text{---} \text{---} \parallel \text{---}$ Vcc1<br>Vcc2 |
| 3          | RFOUT      | This pin is AC coupled and matched to 50 Ohms from 2 - 18 GHz | $\text{---} \parallel \text{---} \text{---} \parallel \text{---}$ RFOUT        |

**Assembly Diagram**

**GaAs InGaP HBT MMIC ULTRA LOW  
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**Mounting & Bonding Techniques for Millimeterwave GaAs MMICs**

The die should be attached directly to the ground plane eutectically or with conductive epoxy (see HMC general Handling, Mounting, Bonding Note).

50 Ohm Microstrip transmission lines on 0.127mm (5 mil) thick alumina thin film substrates are recommended for bringing RF to and from the chip (Figure 1). If 0.254mm (10 mil) thick alumina thin film substrates must be used, the die should be raised 0.150mm (6 mils) so that the surface of the die is coplanar with the surface of the substrate. One way to accomplish this is to attach the 0.102mm (4 mil) thick die to a 0.150mm (6 mil) thick molybdenum heat spreader (moly-tab) which is then attached to the ground plane (Figure 2).

Microstrip substrates should be brought as close to the die as possible in order to minimize bond wire length. Typical die-to-substrate spacing is 0.076mm to 0.152 mm (3 to 6 mils).

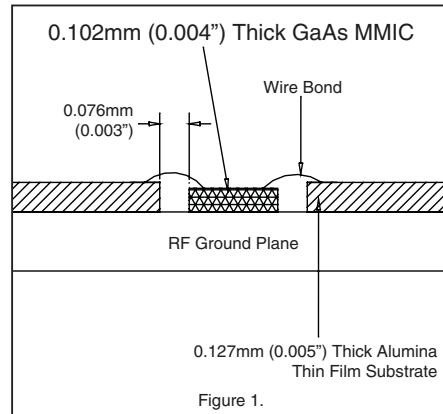


Figure 1.

**Handling Precautions**

Follow these precautions to avoid permanent damage.

**Storage:** All bare die are placed in either Waffle or Gel based ESD protective containers, and then sealed in an ESD protective bag for shipment. Once the sealed ESD protective bag has been opened, all die should be stored in a dry nitrogen environment.

**Cleanliness:** Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

**Static Sensitivity:** Follow ESD precautions to protect against  $> \pm 250$ V ESD strikes.

**Transients:** Suppress instrument and bias supply transients while bias is applied. Use shielded signal and bias cables to minimize inductive pickup.

**General Handling:** Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers. The surface of the chip has fragile air bridges and should not be touched with vacuum collet, tweezers, or fingers.

**Mounting**

The chip is back-metallized and can be die mounted with AuSn eutectic preforms or with electrically conductive epoxy. The mounting surface should be clean and flat.

**Eutectic Die Attach:** A 80/20 gold tin preform is recommended with a work surface temperature of 255 deg. C and a tool temperature of 265 deg. C. When hot 90/10 nitrogen/hydrogen gas is applied, tool tip temperature should be 290 deg. C. DO NOT expose the chip to a temperature greater than 320 deg. C for more than 20 seconds. No more than 3 seconds of scrubbing should be required for attachment.

**Epoxy Die Attach:** Apply a minimum amount of epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip once it is placed into position. Cure epoxy per the manufacturer's schedule.

**Wire Bonding**

Ball or wedge bond with 0.025mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 deg. C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible  $< 0.31$ mm (12 mils).

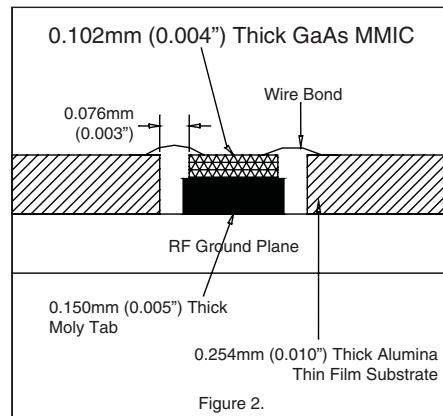


Figure 2.